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IN THE CLAIMS:

Please substitute the following claims for the same-numbered claims in the application:

- 1-7. (Cancelled)
8. (Previously Presented) A conductive interconnection for joining an integrated circuit device to a device carrier, said conductive interconnection comprising:
a polymer having a spherical shape between said integrated circuit device and said device carrier; and
metal projections extending towards said polymer from at least one of said integrated circuit device and said device carrier,
wherein said metal projections each have a same height and extend partially into said polymer across the width of said polymer.
9. (Original) The conductive interconnection in claim 8, wherein said projections have a triangular shape in cross-section.
10. (Original) The conductive interconnection in claim 8, wherein said projections have a cone-shape.
11. (Previously Presented) The conductive interconnection in claim 8, wherein said projections extend from both said integrated circuit device and said carrier.
12. (Original) The conductive interconnection in claim 8, wherein said polymer includes metal particles.
13. (Original) The conductive interconnection in claim 8, wherein said polymer comprises a thermoset polymer.

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14. (Original) The conductive interconnection in claim 8, wherein said polymer comprises a thermoplastic conductive adhesive.
15. (Previously Presented) A conductive interconnection for joining an integrated circuit device to a device carrier, said conductive interconnection comprising:
 - a polymer having a spherical shape between said integrated circuit device and said device carrier; and
 - dendrites within said polymer, wherein said dendrites comprise a plated coating on a conductive material.
16. (Previously Presented) The conductive interconnection in claim 15, wherein said dendrites comprise a plated coating of palladium on a conductive material.
17. (Original) The conductive interconnection in claim 15, wherein said dendrites have an irregular pattern within said polymer.
18. (Original) The conductive interconnection in claim 15, wherein said polymer includes metal particles.
19. (Original) The conductive interconnection in claim 15, wherein said polymer comprises a thermoset polymer.
20. (Original) The conductive interconnection in claim 15, wherein said polymer comprises a thermoplastic conductive adhesive.
21. (Previously Presented) A conductive interconnection for joining an integrated circuit device to a device carrier, said conductive interconnection comprising:

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a polymer having a spherical shape between said integrated circuit device and said device carrier; and

micelle brushes on the outer surface of said polymer,

wherein a first end of said micelle brushes has an affinity for said polymer so as to attach said first end to said polymer and a second end of said micelle brushes has an affinity for metal surfaces so as to attach said second end to said integrated circuit device on one side of said polymer and said device carrier on another side of said polymer.

22. (Original) The conductive interconnection in claim 21, wherein said micelle brushes comprise a reactive moiety with an organic tail.
23. (Original) The conductive interconnection in claim 21, wherein said polymer includes metal particles.
24. (Original) The conductive interconnection in claim 21, wherein said polymer comprises a thermoset polymer.
25. (Original) The conductive interconnection in claim 21, wherein said polymer comprises a thermoplastic conductive adhesive.